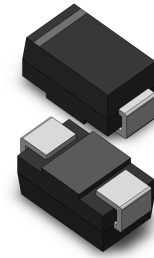


VOLTAGE RANGE: 30 - 60V
CURRENT: 3.0 A

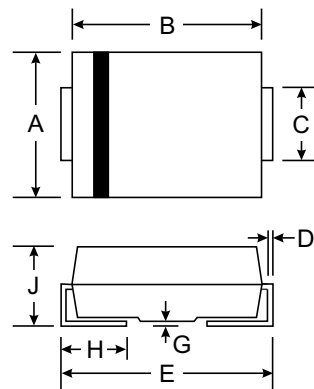
Features

- For Surface Mounted Applications
- High Temperature Metallurgically Bonded Contacts
- Plastic Material - UL Flammability
- Classification 94V-0
- High Reliability
- High Current Capability and Low VF
Submersible Temperature of 265°C for 10 Seconds in Solder Bath



Mechanical Data

- Case: SMA(DO-214AC), Molded Plastic
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Mounting Position: Any
- Weight: 0.064 grams (approx.)



SMA(DO-214AC)		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.10	0.20
H	0.76	1.52
J	2.01	2.62
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Characteristic	Symbol	15MQ030NPBF	15MQ040NPBF	15MQ060NPBF	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	40	60	V
Working Peak Reverse Voltage	V _{RWM}				
DC Blocking Voltage	V _R				
RMS Reverse Voltage	V _{R(RMS)}	21	28	42	V
Average Rectified Output Current @T _L = 105°C	I _O	3.0			A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	80			A
Forward Voltage @I _F = 3.0A	V _{FM}	0.50		0.70	V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}	1.0 20			mA
Typical Thermal Resistance (Note 1)	R _{θJL} R _{θJA}	10 50			°C/W
Operating Temperature Range	T _j	-65 to +125			°C
Storage Temperature Range	T _{STG}	-65 to +150			°C

Note: 1. Mounted on P.C. Board with 8.0mm² copper pad area.

FIG. 1 - FORWARD CURRENT DERATING CURVE

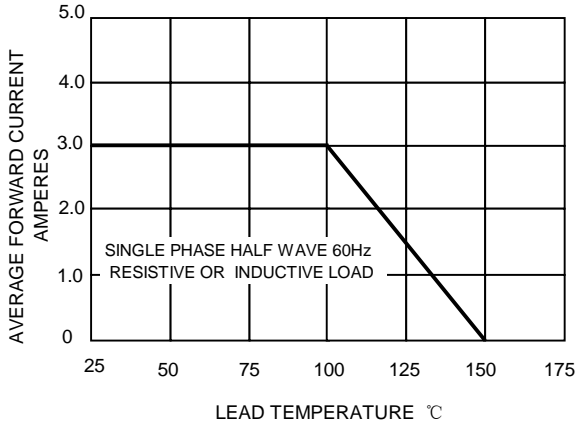


FIG.2 - MAXIMUM NON-REPETITIVE SURGE CURRENT

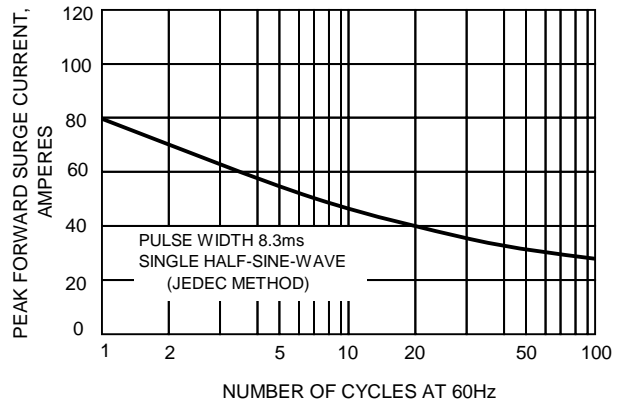


FIG.3-TYPICAL FORWARD CHARACTERISTICS

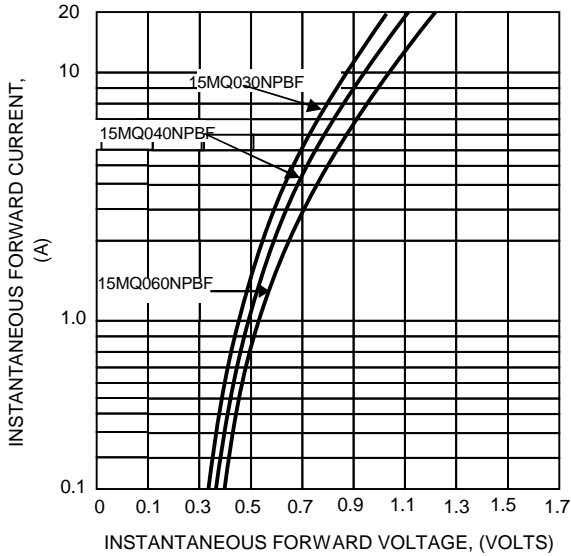


FIG.4-TYPICAL JUNCTION CAPACITANCE

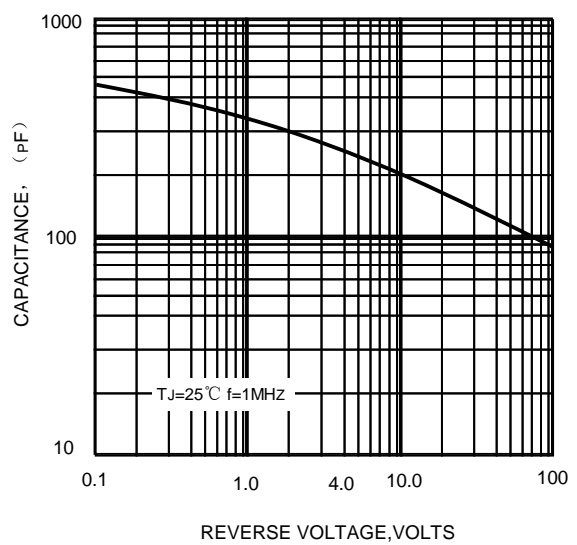


FIG.5-TYPICAL REVERSE CHARACTERISTICS

